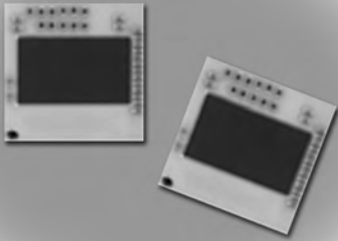
MCM

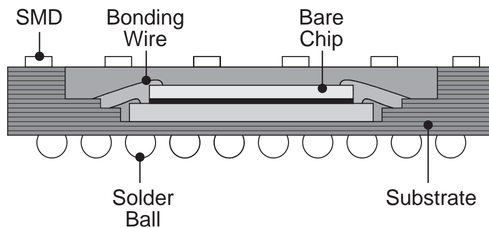
multi-chip module



features

- SMD (Hybrid IC)
- Plural semiconductors in one package offers downsized system with high performance and standardization
- Wiring space saving by multilayer fine patterns on build-up substrate. No signal delay by shortened wiring distance
- High precision modules by function trimming
- Less mounting problem because of the decreasing number of the terminals

construction



Package Specifications

Item	Content
Terminal Pitch	0.8mm~
Mountable Device	• SMD • Bare Chip • Printed Resistor (Trimable)
Package	• SON • BGA • LGA
Substrate for Package	• FR-4 • FR-5 • Alumina • LTCC

Mounting Specifications

Item		Unit	Min.	Std.	Max.	Note
Substrate Dimension		mm	50 x 20	120 x 100	320 x 140	
Substrate Thickness		mm	0.3	—	1.6	
Bare Chip Pad Pitch		μm	100	—	—	
Bare Chip Pad Dimension		μm	70	—	—	
Bare Chip Thickness		mm	0.1	0.2	—	
Molding Height		mm	0.3	1.0	1.2	Height from chip surface
Wire Length		mm	0.3	—	3.0	
Wire Loop Height		μm	100	200	—	
Wire Diameter	Al	μm	200	300	500	for Power Module
	Au		20	25	40	
Plating		Electrical/nonelectrical Au Plating				
Substrate		• FR-4 • FR-5 • Alumina • LTCC • FPC				

substrates & others

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use. 12/17/11